ABSTRACT OF THE DISCLOSURE

DICING DIE-BONDING FILM

A dicing die-bonding film has a supporting substrate, an adhesive layer formed on the supporting substrate, and a die-bonding adhesive layer formed on the adhesive layer, and further has a mark for recognizing the position of the die-bonding adhesive layer. It is possible to provide a dicing die-bonding film in which in the case a semiconductor wafer and the dicing die-bonding film are stuck onto each other, the position of the die-bonding adhesive layer in the film can be recognized.

(Figure 1b)